

**FEATURES**

■ **HIGH POWER**

P1dB=36.5dBm at 5.3GHz to 5.9GHz

■ **HIGH GAIN**

G1dB=10.5dB at 5.3GHz to 5.9GHz

■ **BROAD BAND INTERNALLY MATCHED FET**

■ **HERMETICALLY SEALED PACKAGE**

**RF PERFORMANCE SPECIFICATIONS ( Ta= 25°C )**

CHARACTERISTICS	SYMBOL	CONDITIONS	UNIT	MIN.	TYP.	MAX.
Output Power at 1dB Gain Compression Point	P1dB	VDS= 10V f = 5.3 to 5.9GHz	dBm	35.5	36.5	—
Power Gain at 1dB Gain Compression Point	G1dB		dB	9.5	10.5	—
Drain Current	IDS1		A	—	1.1	1.3
Gain Flatness	ΔG		dB	—	—	±0.6
Power Added Efficiency	ηadd		%	—	37	—
3rd Order Intermodulation Distortion	IM3		Two-Tone Test Po= 25.5dBm	dBc	-44	-47
Drain Current	IDS2	(Single Carrier Level)	A	—	1.1	1.3
Channel Temperature Rise	ΔTch	(VDS X IDS +Pin- P1dB) X Rth(c-c)	°C	—	—	80

**Recommended gate resistance(Rg) : Rg= 150 Ω(MAX.)**

**ELECTRICAL CHARACTERISTICS ( Ta= 25°C )**

CHARACTERISTICS	SYMBOL	CONDITIONS	UNIT	MIN.	TYP.	MAX.
Transconductance	gm	VDS= 3V IDS= 1.5A	mS	—	900	—
Pinch-off Voltage	VGSoff	VDS= 3V IDS= 15mA	V	-1.0	-2.5	-4.0
Saturated Drain Current	IDSS	VDS= 3V VGS= 0V	A	—	2.6	—
Gate-Source Breakdown Voltage	VGSO	IGS= -50μA	V	-5	—	—
Thermal Resistance	Rth(c-c)	Channel to Case	°C/W	—	4.5	6.0

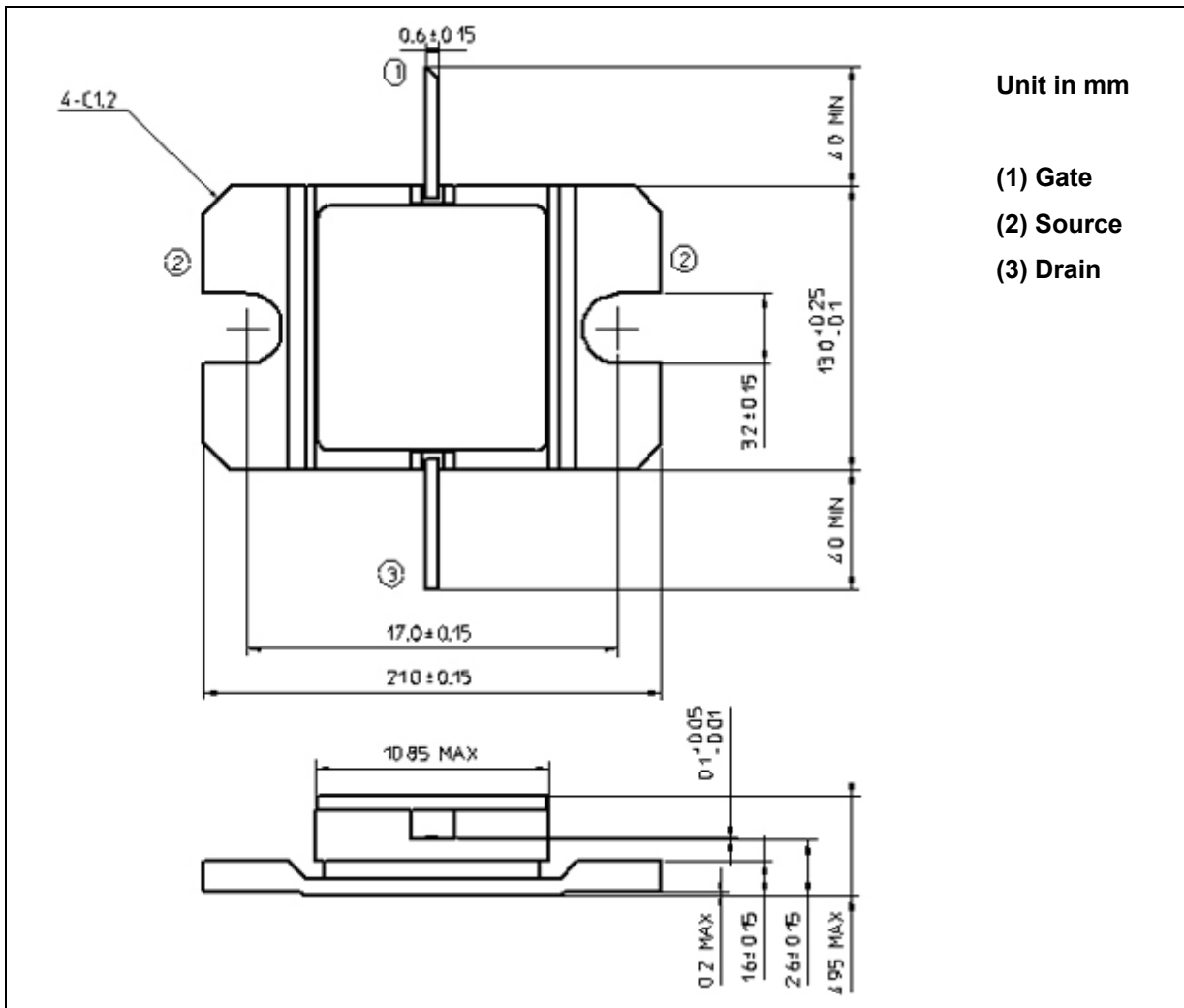
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The information contained herein is subject to change without prior notice. It is therefor advisable to contact TOSHIBA before proceeding with design of equipment incorporating this product.

**ABSOLUTE MAXIMUM RATINGS ( Ta= 25°C )**

CHARACTERISTICS	SYMBOL	UNIT	RATING
Drain-Source Voltage	VDS	V	15
Gate-Source Voltage	VGS	V	-5
Drain Current	IDS	A	3.5
Total Power Dissipation (Tc= 25 °C )	PT	W	25
Channel Temperature	Tch	°C	175
Storage	Tstg	°C	-65 to +175

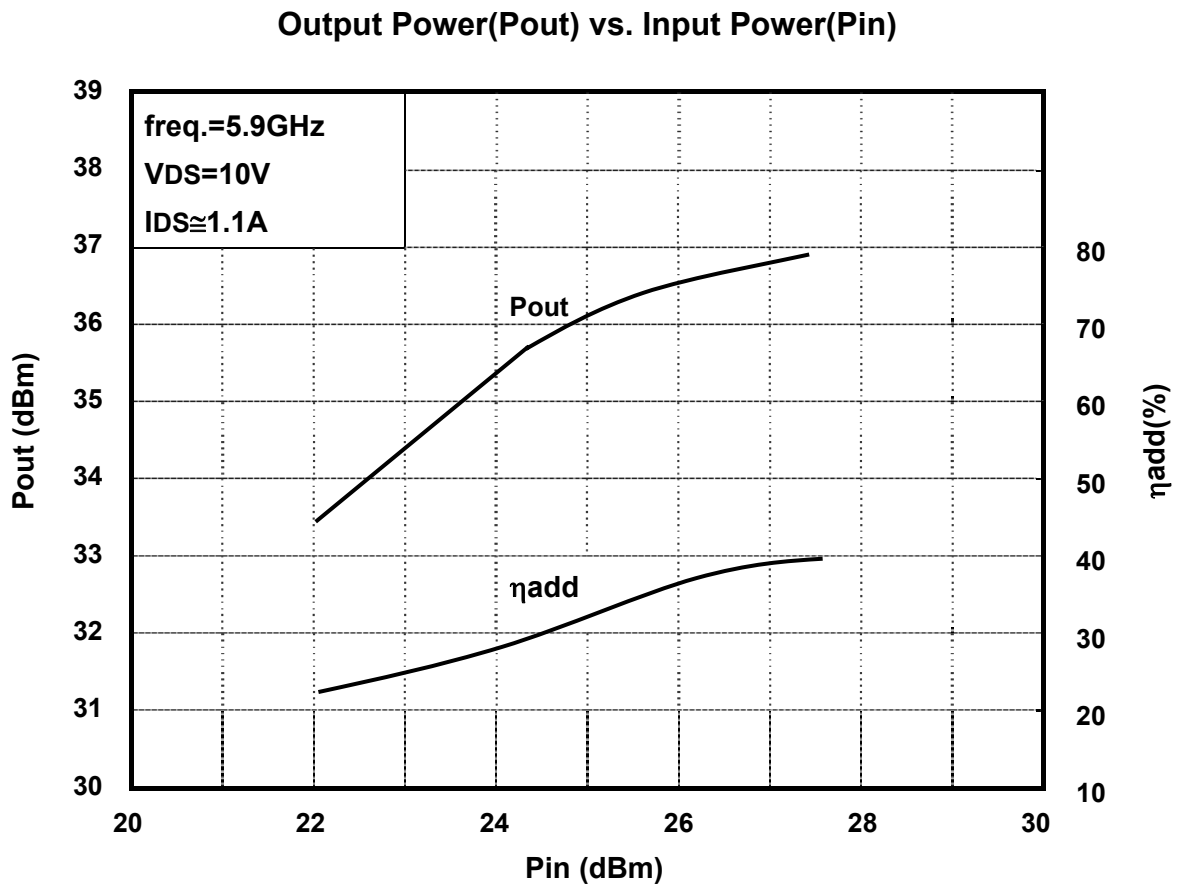
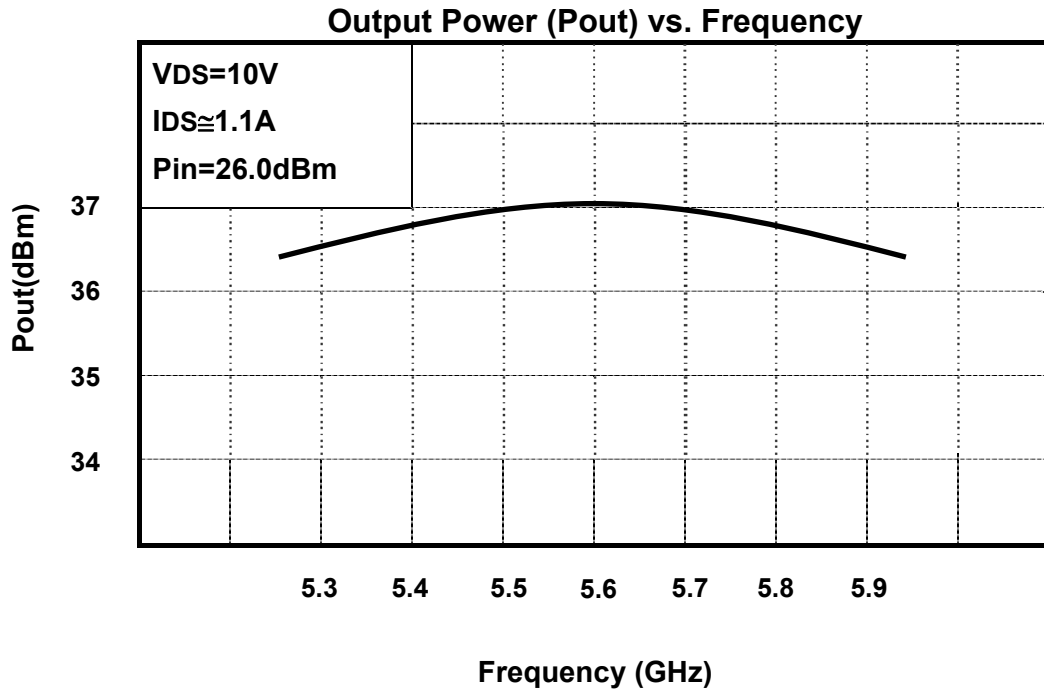
**PACKAGE OUTLINE (2-11D1B)**



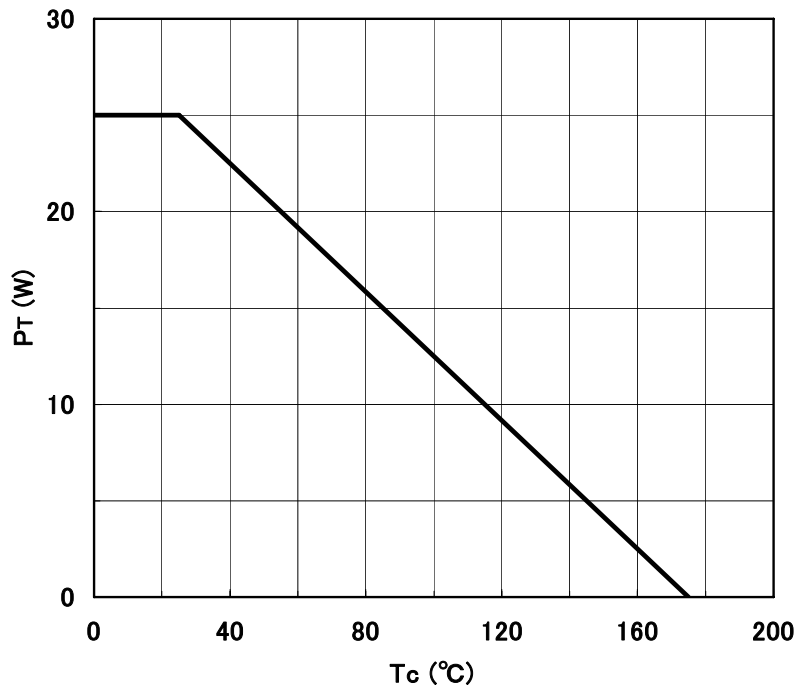
**HANDLING PRECAUTIONS FOR PACKAGE MODEL**

Soldering iron should be grounded and the operating time should not exceed 10 seconds at 260°C.

## RF PERFORMANCE



### Power Dissipation vs. Case Temperature



### IM3 vs. Output Power Characteristics

